L Number	Hits	Search Text	I DD	
1	216927		DB USPAT;	Time stamp
		diepox?\$3 or polyepox?\$3 or diglycidyl\$ or polyglycidyl\$	US-PGPUB; EPO; JPO; DERWENT;	2003/04/15 10:52
2	2605379	semiconductor or electronic or printed adj circuit or wiring adj board or wiring adj substrate	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/04/15 10:52
4	382884	roughening or roughen or etch or etching	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/04/15 10:59
5	10519	((epox?\$3 near (resin\$ or novola?)) or diepox?\$3 or polyepox?\$3 or diglycidyl\$ or polyglycidyl\$) and (semiconductor or electronic or printed adj circuit or wiring adj board or wiring adj substrate) and (roughening or roughen or etch or etching)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 10:59
6	168132	butadiene or nbr or ctbn or polybutadiene	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/15 11:02
7	1787	<pre>(((epox?\$3 near (resin\$ or novola?)) or diepox?\$3 or polyepox?\$3 or diglycidyl\$ or polyglycidyl\$ ) and (semiconductor or electronic or printed adj circuit or wiring adj board or wiring adj substrate ) and (roughening or roughen or etch or etching)) and (butadiene or nbr or ctbn or polybutadiene )</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 11:02
8	62145	oxidizing adj agent	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/15 11:03
9	126	<pre>((((epox?\$3 near (resin\$ or novola?)) or diepox?\$3 or polyepox?\$3 or diglycidyl\$ or polyglycidyl\$) and (semiconductor or electronic or printed adj circuit or wiring adj board or wiring adj substrate) and (roughening or roughen or etch or etching)) and (butadiene or nbr or ctbn or polybutadiene)) and (oxidizing adj agent)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 11:08
10	2	"09046046"	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/04/15 11:09
_	216927	<pre>(epox?\$3 near (resin\$ or novola?)) or diepox?\$3 or polyepox?\$3 or diglycidyl\$ or polyglycidyl\$</pre>	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/04/15 10:52
_	2605379	semiconductor or electronic or printed adj circuit or wiring adj board or wiring adj substrate	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/04/15 10:52
-	62145	oxidizing adj agent	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/15 11:03

	-,			
_	311	embedding adj resin	USPAT;	2003/04/15 08:58
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	96	//	IBM_TDB	
	96	( ( op one ) of novoid: / ) of	USPAT;	2003/04/15 08:58
		diepox?\$3 or polyepox?\$3 or diglycidyl\$ or	US-PGPUB;	
		polyglycidyl\$) and (embedding adj resin)	EPO; JPO;	
	1		DERWENT;	
_	10	/oridining add agents	IBM_TDB	
	10	I the second and agone, and the theory and	USPAT;	2003/04/15 09:05
	İ	(resin\$ or novola?)) or diepox?\$3 or polyepox?\$3 or diglycidyl\$ or	US-PGPUB;	
		polyepox:35 or digiyoldy15 or	EPO; JPO;	
		polyglycidyl\$) and (embedding adj resin))	DERWENT;	
_	20785	roughening	IBM_TDB	
	20703	Toughening	USPAT;	2003/04/15 10:52
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	7	((epox?\$3 near (resin\$ or novola?)) or	IBM_TDB	
	1	diepox?\$3 or polyepox?\$3 or diglycidyl\$ or	USPAT;	2003/04/15 09:06
		polyglycidyl\$) and (semiconductor or	US-PGPUB;	
		electronic or printed adj circuit or	EPO; JPO;	
		wiring adj board or wiring adj substrate)	DERWENT;	
		and (embedding adj resin) and roughening	IBM_TDB	
_	8	(embedding adj resin) and roughening	USPAT;	2002/04/15 20 10
		tone odding day resin, and roughening	US-PGPUB;	2003/04/15 09:12
		•	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	168132	butadiene or nbr or ctbn or polybutadiene	USPAT;	2003/04/15 11:02
		To the state of polybacacione	US-PGPUB;	2003/04/13 11:02
			EPO; JPO;	-
			DERWENT;	
			IBM TDB	
-	28579		USPAT;	2003/04/15 09:13
		diepox?\$3 or polyepox?\$3 or diglycidyl\$ or	US-PGPUB;	2000,01,13 03.13
		polyglycidyl\$) and (butadiene or nbr or	EPO; JPO;	
		ctbn or polybutadiene)	DERWENT;	
			IBM TDB	
-	656	( ( '	USPAT;	2003/04/15 09:13
	[	diepox?\$3 or polyepox?\$3 or diglycidyl\$ or	US-PGPUB;	
		polyglycidyl\$) and (butadiene or nbr or	EPO; JPO;	
		ctbn or polybutadiene)) and roughening	DERWENT;	
		////	IBM_TDB	
	1	((((epox?\$3 near (resin\$ or novola?)) or	USPAT;	2003/04/15 09:13
		diepox?\$3 or polyepox?\$3 or diglycidyl\$ or	US-PGPUB;	
		polyglycidyl\$) and (butadiene or nbr or	EPO; JPO;	
		ctbn or polybutadiene)) and roughening)	DERWENT;	
_	359	and (embedding adj resin)	IBM_TDB	
	339	((((epox?\$3 near (resin\$ or novola?)) or	USPAT;	2003/04/15 09:15
		<pre>diepox?\$3 or polyepox?\$3 or diglycidyl\$ or polyglycidyl\$) and (butadiene or nbr or</pre>	US-PGPUB;	
İ		ctbn or polybutadiene)) and roughening)	EPO; JPO;	
		and (semiconductor or electronic or	DERWENT;	
		printed adj circuit or wiring adj board or	IBM_TDB	
		wiring adj substrate)		
		aaj babbetace/		